

OpenVPX Backplanes Technical Reference Guide

SYSTEMS SOLUTIONS

ENCLOSURES & COMPONENTS

ROTARY SWITCHES

CABINETS

ARCHITECTURE

The OpenVPX reference guide provides relevant reference material for Elma's OpenVPX backplanes. The information provided may change at anytime. OpenVPX is a standard that defines system level interoperability for multi-vendor, multi-module, integrated systems environments. The OpenVPX standard defines clear interoperability points necessary for integration from module to module, module to backplane and backplane to chassis.

OpenVPX purpose:

- Control and manage the assignment of OpenVPX pins to functional planes in an interoperable architecture
- To get a high-degree of interoperability, while leaving room for sensor- /application-specific augmentation
- To make the process of developing OpenVPX-based solutions from the lab to the field much more efficient in cost, time, quality, and repeatability

OpenVPX provides a descriptive language for identifying slot and module requirements and backplanes' capability. It also provides with the part number configuration more information on the control and fabric planes, including the signal speeds.

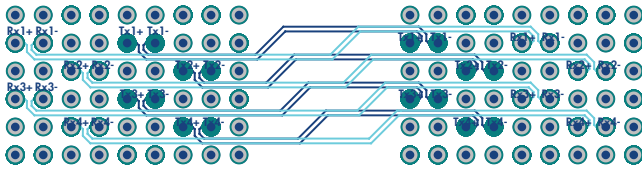
VITA FAMILY OF STANDARDS

The VITA trade association provides members with the ability to develop and to promote open technology standards. The VITA Standards Organization (VSO) is an ANSI-accredited group that provides members with a means to work together to define and develop key computer specifications such as the family of OpenVPX standards, which include VITA 46.x, VITA 48.x, and VITA 65. Elma is a key contributor to the Working Groups related to OpenVPX.

42	XMC mezzanine cards
46.0	OpenVPX
46.1	Parallel VME on OpenVPX
46.3	RapidIO on OpenVPX
46.30 & .31	Higher Data Rate VPX
46.4	PCI Express on OpenVPX
46.6	Gigabit Ethernet Control Plane on OpenVPX
46.7	10 G Ethernet on OpenVPX
46.8	VDSTU InfiniBand on OpenVPX
46.9	Rear IO on OpenVPX
46.10	OpenVPX RTM
46.11	System Management on OpenVPX
47.1-3	Environmental
48.0 – 48.8	OpenVPX REDI: Mechanical Cooling
49.0	Radio Transport & RF Signals
57.1 – 57.2	FMC: FPGA Mezzanine Cards Base
60	Viper connector
61	Alternate XMC connector

62	OpenVPX power supplies
63	Hypertronics connector
62.1-2	VPX Power module
65.0	OpenVPX
65.1	New Slot and Module Profiles
66.0	Optical Overview
66.1	Optical Full size Dual MT variant
66.2	Optical ARINC 801 Termini variant
66.3	Optical Mini Expanded Beam
66.4	Optical Half size MT variant
67.0	RF and Mixed Signal overview
67.1	3U RF
67.2	6U RF
67.3	Flexible multi-level RF on OpenVPX
68	SpaceVPX
68.0	VDSTU OpenVPX SI
68.1	VDSTU OpenVPX SI backplane
68.2	OpenVPX SI Mezzanine (under development)

PIPES: FAT, THIN, ULTRA THIN



Fat Pipe: A channel that is comprised of four links (4 Tx pairs + 4 Rx pairs) is now being referred to as a Fat Pipe or by use of the x4 nomenclature. 100GBASE-KR4, 40GBASE-KR4, 10GBASE-KX4, 10GBase-BX4, 10GBASE-T, PCIe-x4, sRIO-x4, Infiniband-x4



Thin Pipe: A channel that is comprised of two links (2 Tx pairs + 2 Rx pairs) is now being referred to as a Thin Pipe or by use of the x2 nomenclature. 10/100/1000BASE-T, PCIe-x2, sRIO-x2, Infiniband-x2



Ultra-thin Pipe: A channel that is comprised of one link (1 Tx pair + 1 Rx pair) is now being referred to as an Ultra Thin Pipe or by use of the x1 nomenclature. 10GBASE-KR, 1GBASE-KX, PCIe-x1, sRIO-x1, Infiniband-x1a

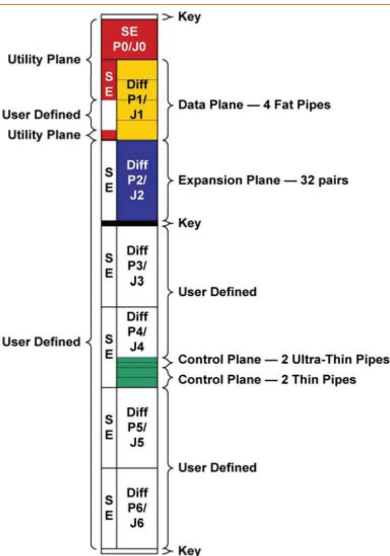


SLOT PROFILES

VITA 65 defines OpenVPX in terms of four types of Profiles: Slot Profiles, Backplane Profiles, Module Profiles and Chassis Profiles. Slot Profiles have a type, board size and clock variation. Slots have rows that are defined to support a variety of Pipe sizes or module apertures. Slot Profiles define where pipes or apertures are located and also indicated user defined wafer locations.

Backplane Profiles define how the Slots are interconnected. Backplane Profiles also define the bandwidth capability of the Pipes. Module Profiles indicate which Pipes or Apertures are supported and the signaling protocol and data rate associated with each Pipe. A Module Profile are fully compatible with a single Slot Profile but can be used in Slots that do not fully support all the defined channels.

The system integrator must ensure that pipes that are connected together in a backplane have modules that support the same signaling protocols. The chart below indicates how the various features of a Slot Profile are described.



SLTU y - PAY - nXnXnX-1X.x.x-n

Board Size
U = 3 or 6

y = Clock variations
• p = parallel termination
• s = series termination
• x = radial - not defined
• Omitted field = bussed

Slot type
• PAY = payload
• STO = storage
• PER = peripheral
• SVH = switch
• TIM = timing

n = # pipes or connector patterns

VITA 65 Sections 10 or 14

X = Type of Pipes or Aperture
Pipes (number of diff. pairs or discrete fibers)
• S = Single Pipe (1)
• U = Ultra-thin (2)
• T = Thin (4)
• F = Fat (8)
• M = Ten (10)
• W = Twelve (12)
• D = Double (16)
• Q = Quad (32)
• O = Octal (64)
Connector aperture name (Connector Module size)
• A = 66.1 (full)
• B = 66.2 (full)
• C = 66.3 (full)
• E = 66.4/ 67.1/ 67.3A (half)
• G = 67.2/ 67.3B (full)
• H = 67.3C (full new)
• J = 67.3D (half new)
• K = 67.3E (full+half new)

n = a line in the Slot Profile spreadsheet identifying specific connector aperture pattern (if any) and RF or optical module population (if any)

Note: That order of Pipes is from top to bottom in the physical slot

CHALLENGING ENVIRONMENTS

OpenVPX systems are often deployed in harsh environments across a range of defense and industrial applications where excessive shock, vibration and high ambient temperatures are common.



AMPS - THE ALTERNATE MODULE PROFILE SCHEME

An important tool for defining what protocols and capabilities an individual plug-in card can support is the Alternate Module Profile Scheme, or AMPS. AMPS was developed in response to what was seen as an explosion of options being captured in VITA 65.1, which was resulting in a ballooning document that many were finding increasingly difficult to work with. VNX+ will adopt the AMPS approach for defining supported protocols for defined communications ports.

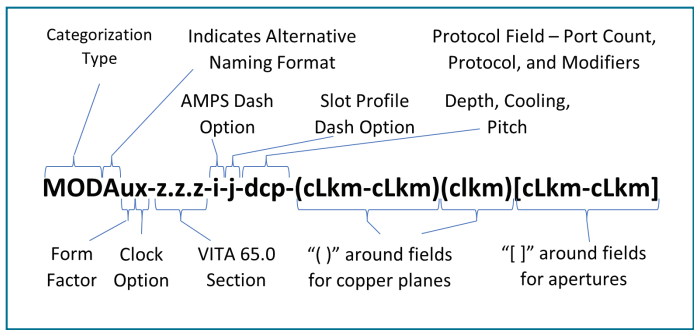


Figure 1: AMPS String Template

AMPS is a string built using the template in Figure 1. The supplier builds a string for their particular VPX plug-in card by filling the strings with the appropriate code in each field of the template. The early part of the string describes the general data about the card including the size (3U or 6U), VITA 65.0 section, and the slot profile "dash" option (indicating the aperture fill block pattern). The rest of the string is used to describe various communications ports found in the slot profile, what protocols the plug-in card supports, and any modifiers that are needed to describe the particular capabilities of each port.

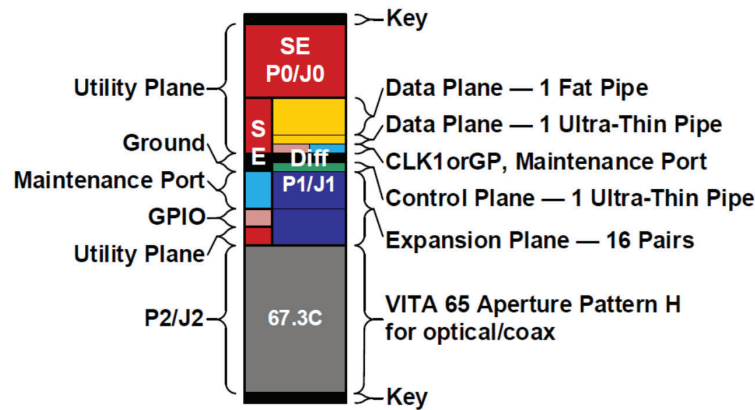


Figure 2: SLT3-PAY-1F1U1S1S1U1U2F1H-14.6.11-n slot profile

An example of an AMPS string for a sample SLT3-PAY-1F1U1S1S1U1U2F1H-14.6.11-1 Payload card is:

MODA3-14.6.11-0-F2C-(E8 - E2)(P3F-P3F)(E2)(N-G2)[N]

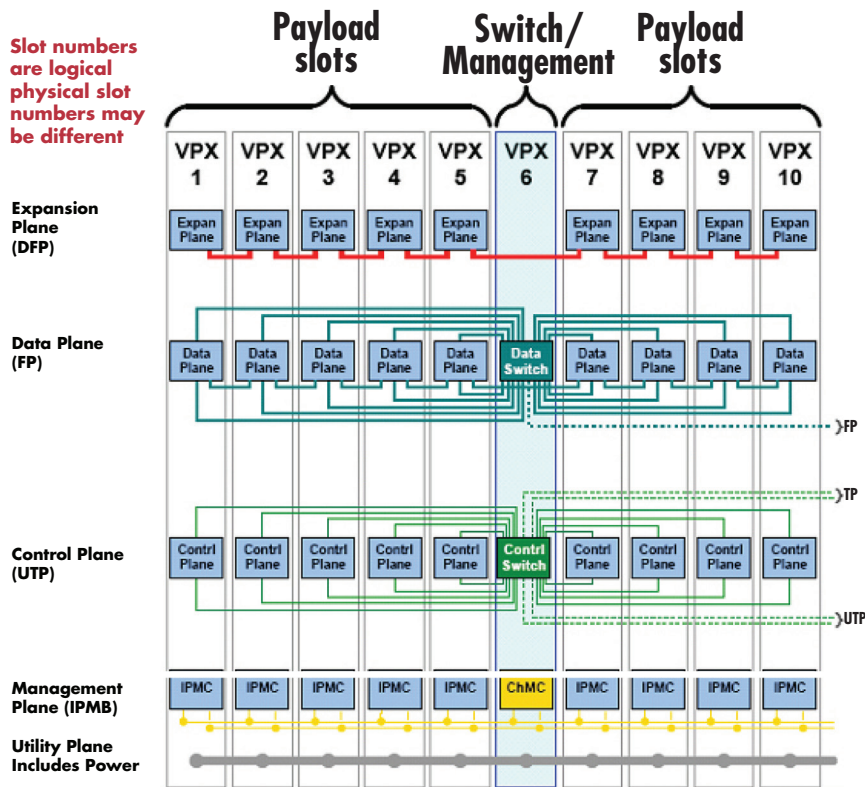
Which says that this card supports:

- Slot profiles is 14.6.11
- The aperture is empty
- Board is 1" conduction cooled
- Data Plane supports 40GBASE-KR4 on the Fat Pipe, and 10GBASE-KR on the Ultra Thin Pipe, and both properly auto-negotiate
- Expansion Plane supports PCI Express Gen3 and correctly auto-negotiates
- Control Plane supports 10GBASE-KR and properly auto-negotiates
- There is no GPIO and CLK1 supports LVDS signalling

For more information on AMPS strings please refer to the VITA 65.0 standard document.

TOPOLOGIES

The backplane configuration examples show the connectivity across the backplane for various planes. This includes the routing topology across the data plane and the connections across the expansion, control, management and utility planes. They also provide an illustration of the slot types, whether payload, switch or legacy bus slots.



DATA RATES

OpenVPX defines the data rates of each Plane (Control, Data and Expansion) on the Backplane. They begin at 1.25 Gbaud/link and currently exceed 25 Gbaud/link:

Note: Gbaud refers to the useful data transmitted per second. Gbps is usually larger and includes additional signals such as parity bits and packet headers.

Backplane designs for the highest level of signal integrity

At speeds up to 100GBASE-KR4, every feature of backplane design can influencesignal integrity (SI) – every trace, layer separation, turn bend, via, via transition,etc. Elma’s signal integrity analysis and simulations consider every element in the channel to ensure optimal performance. We focus on each feature individually to model the complete channel and optimize the return loss for each. Once modeled, they are concatenated together along with the trace and connector models to create the complete channel.

Today’s critical high-speed systems require nothing less than reliable, repeatable solutions - every time.

Profile Name	Mechanical		Slot Profiles and Section		Gbaud Rate
	Pitch (in)	RTM Conn	Payload	Payload or Peripheral	Data Plane Channel
BKP3-CEN03-15.2.9-1	1.0	VITA 46.10	SLT3-PAY-2F-14.2.7	SLT3-PER-1F-14.3.2	2.5
BKP3-CEN03-15.2.9-2	1.0	VITA 46.10	SLT3-PAY-2F-14.2.7	SLT3-PER-1F-14.3.2	5.0
BKP3-CEN03-15.2.9-3	1.0	VITA 46.10	SLT3-PAY-2F-14.2.7	SLT3-PER-1F-14.3.2	6.25
BKP3-CEN03-15.2.9-4	1.0	VITA 46.10	SLT3-PAY-2F-14.2.7	SLT3-PER-1F-14.3.2	8.0

UTILITY SIGNALS

J0/P0 Pin/Signal	Description
Vs1	High Voltage Power Input 1 Voltage specified in VITA 65. Capability per VITA 46.0 Table 4-5
Vs2	High Voltage Power Input 2 Voltage specified differently for 3U or 6U in VITA 65. Capability per VITA 46.0 Table 4-5
Vs3	Low Voltage Power Input 3 Voltage specified in VITA 65. Capability per VITA 46.0 Table 4-5
GA[4:0]*, GAP*	Geographical Address Inputs 0-4, Parity. Grounded in each slot per VITA 46.0 Table 7-1.
SM[3:0]	System Management connections bussed per Phillips Semiconductor I2C-Bus Specification, Version 2.1, January 2000
AUX_CLK+/-	Optional auxiliary reference clock (see ANSI/VITA 65) matched better than 8.5 pS and differentially terminated to 130 Ohms $\pm$ 10%. Often used for 1PPS precision clock.
3.3V_AUX	3.3V Auxiliary power, System Management, 1.0 A per slot.
+/- 12V_AUX	Auxiliary Power Supplies, 1.0 A per slot.
SYSRESET*	System Reset, bussed to all slots & terminated w 5% 220-ohm pull-up resistors to 3.3V AUX & 1.8K-ohm pull-down to GND or equiv.
REF_CLK+/-	Reference Clock 25 or 100 MHz matched better than 8.5 pS and differentially terminated at each end with a resistor of 61.9 Ohms $\pm$ 1%.
NVMRO	Non-Volatile Memory Read Only, bussed to all slots and pulled to 3.3V_AUX through 5% 220 ohm resistor
TCK, TMS, TRST*, TDI, TDO	JTAG Signals, not bussed or terminated on the backplane.
No Pad	The construction of the connector wafer is such that there is no circuit pad in this location

JJ1/P1 Pin/Signal	Description
GDiscrete1	Optional single ended general purpose I/O signal, bussed to each slot.
P1-VBAT	Battery Voltage, Bussed, 3V +/- 15% source on the backplane.
SYS_CON*	When grounded the backplane the SYS_CON mode is set. Implemented in by a jumper at any slot to be so designated.
MaskableReset*	Optional local reset input to Plug-In Module in addition to global SYSRESET*. Implemented as "opt-in" via jumper at each slot.

Table 3.7-2 Utility Plane Signals on J0

	Row i	Row i	Row h	Row g	Row f	Row e	Row d	Row c	Row b	Row a
1	GDiscrete1	1	Vs1	Vs1	Vs1	No Pad*	Vs2	Vs2	Vs2	Vs2
2	GND	2	Vs1	Vs1	Vs1	No Pad*	Vs2	Vs2	Vs2	Vs2
3	P1-VBAT	3	Vs3	Vs3	Vs3	No Pad*	Vs3	Vs3	Vs3	Vs3
4	GND	4	GND	SM2	SM3	-12V_Aux	GND	SYSRESET*	NVMRO	GND
5	SYS_CON*	5	GND	GAP*	GA4*	3.3V_Aux	GND	SM0	SM1	GND
6	GND	6	GND	GA3*	GA2*	+12V_Aux	GND	GA1*	GA0*	GND
7	Reserved	7	TCK	GND	GND	TDI	GND	GND	TMS	TRST*
8	GND	8	GND	REF_CLK-	REF_CLK+	GND	GND	AUX_CLK-	AUX_CLK+	GND
9	UD	← UD pins in Row i can be assigned by Slot Profiles in Sections 10 and 14. The pairs on Rows a thru h are assigned by Slot Profiles in Sections 10 and 14.								
10	GND									
11	UD									
12	GND									
13	UD									
14	GND									
15	MaskableReset*									
16	GND									

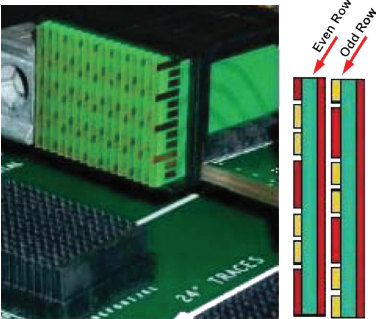
Table 3.7-4 Utility Plane Signals on J1

BACKPLANE AND DAUGHTER CARD PINOUT CHART

This chart shows the specification pinout of both the backplane and daughter card for J2-J6. Note the differences between the plug-in module and the backplane (even and odd pins) for Row E and Row B. Although the number of rows is different, the connector arrangement allows single-ended signals in these areas. The backplane and daughter card connectors mate without issue.

	Row G	Row F	Row E		Row D	Row C	Row B		Row A
	Even	Odd	Even	Odd	Even	Odd	Even	Odd	Even
Back-plane J2-J6	Row i	Row h	Row g	Row f	Row e	Row d	Row c	Row b	Row a
1	SEwafer1	GND	GND-J2	LN0-TD-	LN0-TD+	GND	GND-J2	LN0-RD-	LN0-RD+
2	GND	LN1-TD-	LN1-TD+	GND-J2	GND	LN1-RD-	LN1-RD+	GND-J2	GND
3	SEwafer3	GND	GND-J2	LN2-TD-	LN2-TD+	GND	GND-J2	LN2-RD-	LN2-RD+
4	GND	LN3-TD-	LN3-TD+	GND-J2	GND	LN3-RD-	LN3-RD+	GND-J2	GND
5	SEwafer5	GND	GND-J2	LN4-TD-	LN4-TD+	GND	GND-J2	LN4-RD-	LN4-RD+
6	GND	LN5-TD-	LN5-TD+	GND-J2	GND	LN5-RD-	LN5-RD+	GND-J2	GND
7	SEwafer7	GND	GND-J2	LN6-TD-	LN6-TD+	GND	GND-J2	LN6-RD-	LN6-RD+
8	GND	LN7-TD-	LN7-TD+	GND-J2	GND	LN7-RD-	LN7-RD+	GND-J2	GND
9	SEwafer9	GND	GND-J2	LN8-TD-	LN8-TD+	GND	GND-J2	LN8-RD-	LN8-RD+
10	GND	LN9-TD-	LN9-TD+	GND-J2	GND	LN9-RD-	LN9-RD+	GND-J2	GND
11	SEwafer11	GND	GND-J2	LN10-TD-	LN10-TD+	GND	GND-J2	LN10-RD-	LN10-RD+
12	GND	LN11-TD-	LN11-TD+	GND-J2	GND	LN11-RD-	LN11-RD+	GND-J2	GND
13	SEwafer13	GND	GND-J2	LN12-TD-	LN12-TD+	GND	GND-J2	LN12-RD-	LN12-RD+
14	GND	LN13-TD-	LN13-TD+	GND-J2	GND	LN13-RD-	LN13-RD+	GND-J2	GND
15	SEwafer15	GND	GND-J2	LN14-TD-	LN14-TD+	GND	GND-J2	LN14-RD-	LN14-RD+
16	GND	LN15-TD-	LN15-TD+	GND-J2	GND	LN15-RD-	LN15-RD+	GND-J2	GND

OPENVPX CONNECTOR

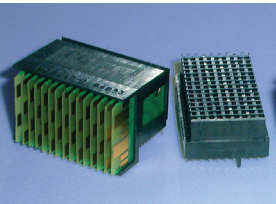


With the exception of J0 rows 1-6, OpenVPX daughter card connectors are constructed of alternating even and odd wafer elements. As a result of this design, the odd wafer rows have a SE pin in daughter card column "g" that corresponds to backplane wafer column "i".

Elma can provide backplanes with either TE MultiGig™ or EPT Velox™ connectors in accordance with ANSI-VITA 46. The EPT Velox™ is Standard on Elma OpenVPX development backplanes.

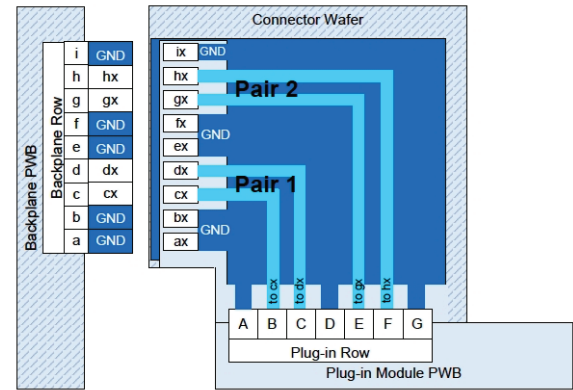
Backplanes can also be assembled with backplane connectors in accordance with ANSI VITA 60 or 63 connectors or a combination of slots fitted with VITA 46, 60 or 63 connectors as they are all footprint compatible, though not intermateable.

CHARACTERISTICS

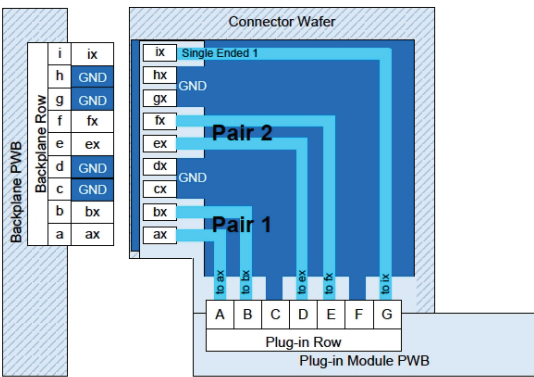


Operating Voltage:	50 Volts AC peak or DC
Current:	1 amp at <30°C (single circuit, free air)
Temperature:	-55°C to 105°C
Insulation resistance:	1000 megohms minimum
Temperature rise vs. current:	30°C maximum temperature at 1 amp load,

ODD AND EVEN WAFER DESIGN

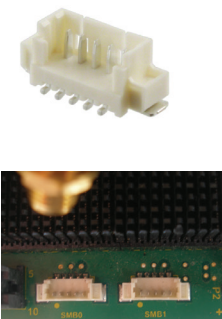


VITA 46 Wafer - Even Differential Pair



VITA 46 Wafer - Odd Differential Pair

IPMB CONNECTOR (SMT)



Number of Positions:	5
Number of Rows:	1
Operating Temperature:	85.0°C (max)
Contact Material:	Phosphor Bronze
Flammability Rating:	UL 94 V-0
Gender:	Male
Current Rating:	1.3A at @ 30°C rise
Mfg Part Number:	Molex PicoBlade(tm) 53398-0571

KEYING GUIDE

OpenVPX alignment and module keying is accomplished by the use of pins on the backplane and sockets on the daughter card. The pins have a flat side that can be oriented in five different positions: 0, 45, 90, 270 or 315 degrees. In standard development backplanes, each slot has a unique key combination.

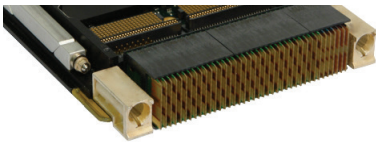
The chart below gives the recommended keying arrangement for 3U or 6U backplanes. Additionally, the key receptacle on the daughter card has electrical contacts so that the keying is part of the OpenVPX safety ground system. The backplane key orientation can be changed by the user, and a daughter card receptacle key can be a full circle without a flat, which allows a daughter card to be placed over backplane keys of any orientation. Double-ended backplane guide modules provide RTM keying and alignment.

Backplane Slot*	Voltage Key Position 1	Key Position 2	Key Position 3
Slot 1	315	270	270
Slot 2	315	315	270
Slot 3	315	0	270
Slot 4	315	45	270
Slot 5	315	90	270
Slot 6	315	270	315
Slot 7	315	315	315
Slot 8	315	0	315
Slot 9	315	45	315
Slot 10	315	90	315
Slot 11	315	270	0
Slot 12	315	315	0
Slot 13	315	0	0
Slot 14	315	45	0
Slot 15	315	90	0
Slot 16	315	270	45
Slot 17	315	315	45
Slot 18	315	0	45
Slot 19	315	45	45
Slot 20	315	90	45
Slot 21	315	270	90
Slot 22	315	315	90
		Backplane	FTM RTM
Front Module		1469491-C	1469492-C
Front Rear Double Key*		1410956-C	1469492-C

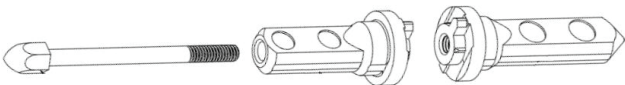
* Double ended for backplane. FTM and RTM use same



Keying Pin



Keying Guide



Double-Ended Guide

OPENVPX - AVAILABLE POWER & VOLTAGE ASSIGNMENTS

The chart below gives maximum power per OpenVPX slot based upon VITA 46 and profiles defined in VITA 65.

Voltage Level	3U watts/slot	6U watts/slot	per wafer due to connector limits
Only 3V	69	N/A	23 Amps†
Only 5V	115	115	23 Amps†
Only 12V*	276	384	23 Amps† (3U), 16 Amps‡ (6U)
VS1, VS2, and VS3	240	348	12 Amps§
Only 48v per VITA 46	N/A	768	16 Amps‡ (VS1 and VS2)

Note: †= 1 power wafer used, ‡=2 power wafers used, §=3 power wafers used

The assignment of voltages on VS1, VS2 and VS3 is different for 3U and 6U cards. In addition, more voltage options are allowed for VS1 and VS2 in VITA 46 than are currently defined within VITA 65.

SIGNAL ASSIGNMENTS FOR THE J0 CONNECTOR PER VITA 46.0 AND VITA 65

	Row i	Row h	Row g	Row f	Row e	Row d	Row c	Row b	Row a
1	Vs1	Vs1	Vs1	Vs1	No Pad*	Vs2	Vs2	Vs2	Vs2
2	Vs1	Vs1	Vs1	Vs1	No Pad*	Vs2	Vs2	Vs2	Vs2
3	Vs3	Vs3	Vs3	Vs3	No Pad*	Vs3	Vs3	Vs3	Vs3
4	GND	SM2	SM3	GND	-12V_Aux	GND	SYSRESET'	NVMRO	GND
5	GND	GAP*	GA4*	GND	3.3V_Aux	GND	SM0	SM1	GND
6	GND	GA3*	GA2*	GND	+12V_Aux	GND	GA1'	GA0*	GND
7	TCK	GND	GND	TDO	TDI	GND	TMS	TMS	TRST*
8	GND	REF_CLKK-	REF_CLK+	GND	GND	AUX_CLK-	AUX_CLK+	GND	GND

3U POWER ASSIGNMENTS FOR THE J0 CONNECTOR PER VITA 65

	Row i	Row h	Row g	Row f	Row e	Row d	Row c	Row b	Row a
1	12V	12V	12V	12V	No Pad*	3V	3V	3V	3V
2	12V	12V	12V	12V	No Pad*	3V	3V	3V	3V
3	5V	5V	5V	5V	No Pad*	5V	5V	5V	5V
4	GND	SM2	SM3	GND	-12V_Aux	GND	SYSRESET'	NVMRO	GND
5	GND	GAP*	GA4*	GND	3.3V_Aux	GND	SM0	SM1	GND
6	GND	GA3*	GA2*	GND	+12V_Aux	GND	GA1'	GA0*	GND
7	TCK	GND	GND	TDO	TDI	GND	TMS	TMS	TRST*
8	GND	REF_CLKK-	REF_CLK+	GND	GND	AUX_CLK-	AUX_CLK+	GND	GND

6U POWER ASSIGNMENTS FOR THE J0 CONNECTOR PER VITA 65

	Row i	Row h	Row g	Row f	Row e	Row d	Row c	Row b	Row a
1	12V	12V	12V	12V	No Pad*	12V	12V	12V	12V
2	12V	12V	12V	12V	No Pad*	12V	12V	12V	12V
3	5V	5V	5V	5V	No Pad*	5V	5V	5V	5V
4	GND	SM2	SM3	GND	-12V_Aux	GND	SYSRESET'	NVMRO	GND
5	GND	GAP*	GA4*	GND	3.3V_Aux	GND	SM0	SM1	GND
6	GND	GA3*	GA2*	GND	+12V_Aux	GND	GA1'	GA0*	GND
7	TCK	GND	GND	TDO	TDI	GND	TMS	TMS	TRST*
8	GND	REF_CLKK-	REF_CLK+	GND	GND	AUX_CLK-	AUX_CLK+	GND	GND

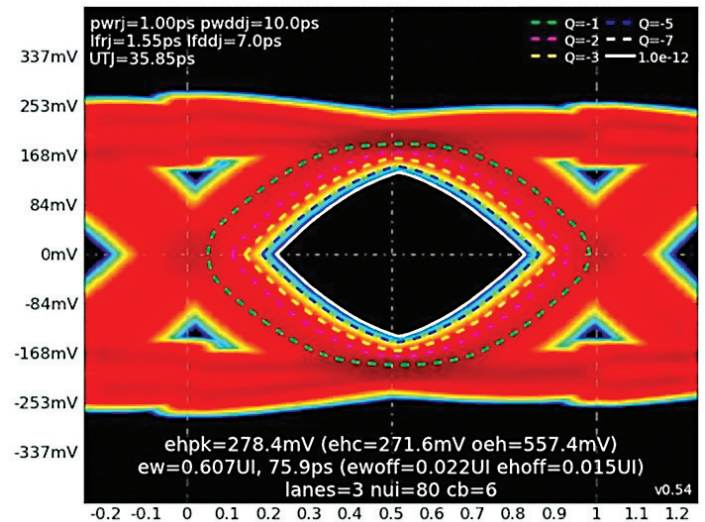
OPENVPX SIGNAL INTEGRITY CONSIDERATIONS

With OpenVPX backplanes pushing the speed envelope, every feature of the design can influence signal integrity – every trace, layer separation, turn bend, via, via transition, etc. Elma's signal integrity analysis and simulations look at the entire channel in order to ensure optimal performance.

Our simulation is very detailed, looking closely at each element in the channel. We focus on each of the various structures and launches, along with lossy trace models, to model the complete channel as accurately as possible. By focusing on each structure individually, we can optimize the return loss for each. Once the structures are modeled, they are concatenated together along with the lossy trace models and connector models to create the complete channel. When there are four complete coupled channels modeled - 2 TX and 2 RX - we utilize a connector model that also has four pairs. Transmission lines are created in W-element tabular format using RLGC, a 2D Field Solver.

The fitted attenuation, IL, ILD, RL and ICR will be compared to the channel requirements. We use symmetry and algebraically add noise components to account for the total noise in the system. This total noise includes the coupled noise generated in the connector via fields as well as the connectors themselves.

We generate S-parameter models and run the simulation in Ansoft HFSS. For instance, when dealing with a typically thick 30-layer N4000-13EPSI backplane design, we need to ensure compliance to the stringent 10 or 25 Gbps KR frequency domain requirements. For each simulation, four complete channels (2-TX and 2-RX) are modeled. These channels are coupled together in the connector via footprints as well as the connector models to account for the total noise generated. We start by modeling the worst-case channel parameters. This would include a channel being routed on the lowest backplane layer (L28) in the stack. We will use the largest multilane connector model available. For PCIe Gen3 or Gen4 analysis, SEASIM is the preferred tool for channel performance. If problems are encountered, specific recommendations for resolving those problems are recommended and verified via additional simulation.



QUALITY BEGINS & ENDS WITH THE CUSTOMER

This is reflected throughout Elma. Our quality procedures meet ISO 9001 & AS9100C standards, ensuring that we meet the most rigorous requirements.



**Elma Electronic Inc. USA**

44350 Grimmer Blvd.
Fremont, CA 94538
P: +1 510 656 3400
F: +1 510 656 3783
sales@elma.com

Optima Stantron

2305 Newpoint Parkway
Lawrenceville, GA 30043
P: +1 770 496 4000
F: +1 770 496 4026
sales@optimastantron.com

Elma Electronic AG, Switzerland

Hofstrasse 93
CH-8620 Wetzikon
P: +41 44 933 41 11
F: +41 44 933 42 15
info@elma.ch

Elma Electronic GmbH, Germany

Stuttgarter Straße 11
D-75179 Pforzheim
P: +49 7231 97 34 0
F: +49 7231 97 34 97
info@elma.de

Elma Electronic UK Ltd.

Solutions House, Fraser Road
Priory Business Park
Bedford MK44 3BF, UK
P: +44 1234 838 822
F: +44 1234 836 650
sales@elma.co.uk
If you are using a satellite navigation device
or internet map to find us, please use the
postcode of our neighbours: MK44 3WH

Elma Electronic France SA

16 rue Hannah Arendt
Parc des Forges
F-67200 Strasbourg
P: +33 3 88 56 72 50
sales@elma-electronic.fr

Elma Electronic Israel Ltd.

34, Modi'in St.
I.Z. Sgula
Petach Tikva 49271
P: +972 3 930 50 25
F: +972 3 931 31 34
sales@elma.co.il

Elma Electronic Technology

(Shanghai) Co., Ltd.
Building#11, No.198
Chang Jian Road
Bao Shan District
Shanghai, PRC, 200949
P: +86 21 5866 5908
F: +86 21 5866 5918
sales@elmachina.com

Elma Asia Pacific Pte. Ltd.

8 Ubi Road 2
07-14
Zervex Building
Singapore 408538
P: +65 6479 8552
F: +65 6479 8662
sales@elma.com.sg

YOUR LOCAL SOLUTION PARTNER